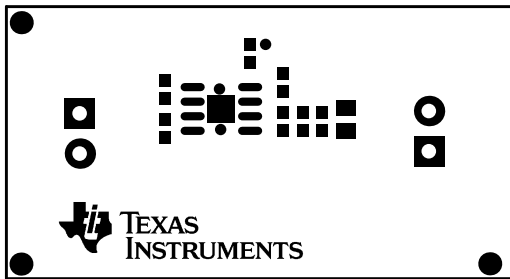
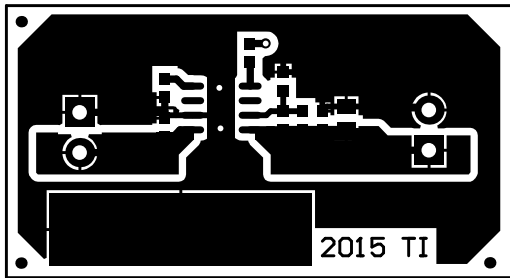


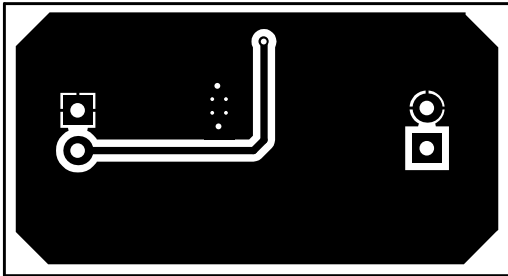
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/26/2015 10:20:44 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/26/2015 10:20:45 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/26/2015 10:20:46 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00597

REV: E1

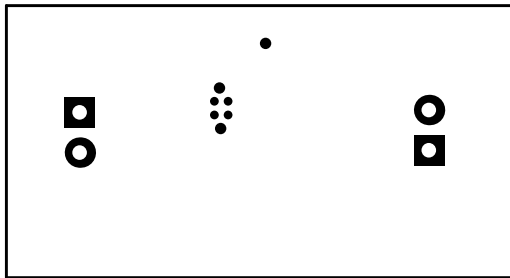
SVN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 6/26/2015 10:20:47 AM

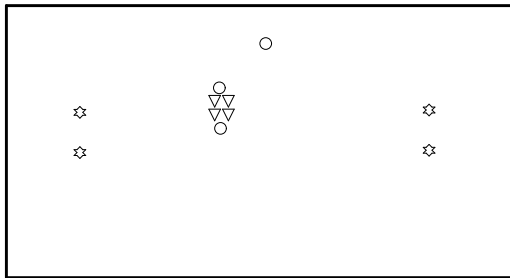
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/26/2015 10:20:47 AM	TEXAS INSTRUMENTS	

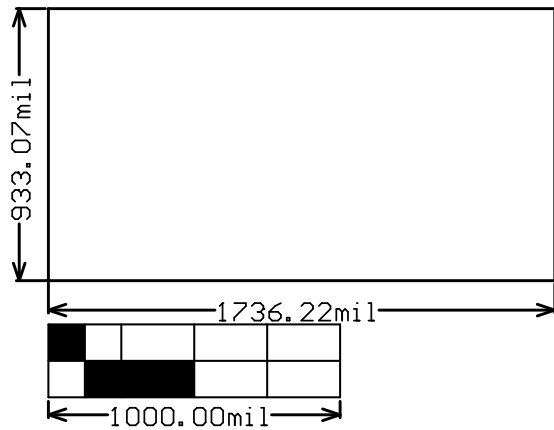


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/26/2015 10:20:48 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	4	12.992mil (0.33mm)	PTH	Round
○	3	20mil (0.508mm)	PTH	Round
☆	4	50mil (1.27mm)	PTH	Round
	11 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/26/2015 10:20:49 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/26/2015 10:20:50 AM	TEXAS INSTRUMENTS	



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